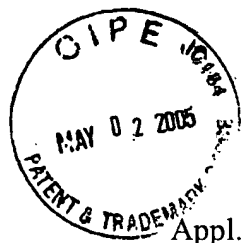


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE COMMISSIONER OF PATENTS

Appl. No. : 10/821,889
Applicant : R Japp et al
Filed : 3/31/04
TC/A.U. : 1756
Examiner :
Docket No. : EI-2-04-005
Title: : **Dielectric Composition For Forming Dielectric Layer For Use In Circuitized Substrates**
Assignee : Endicott Interconnect Technologies, Inc.

Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

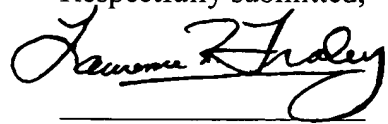
STATUS INQUIRY

Applicants request the status of the above application. The application was filed on 03/31/04. A copy of the return postcard is attached for the Examiner's convenience. A Filing Receipt was received 06/30/04. A copy is attached for the Examiner's convenience. A Change of Correspondence Address was filed 07/20/04. A copy of this return postcard is also attached for the Examiner's convenience.

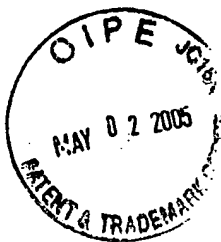
Because Applicants have heard nothing further as of this date, a status is requested. Please advise when we may expect a communication with respect to the above-referenced application. A stamped, self-addressed envelope is enclosed herewith for your use in responding to this request.

An e-mail response to the undersigned at the email address below or a phone response is encouraged to expedite a response to this inquiry.

Telephone: (561) 575-3608
Fax : (561) 745-2741

Respectfully submitted,


Lawrence R. Fraley
Reg. No: 26,885
Attorney for Applicants
Date: April 28, 2005
e-mail: Lawrence.Fraley@eitny.com



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APR 08 2004

Date: 3/30/04
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| <input checked="" type="checkbox"/> IDS/PTO-1449/Refs. | <input type="checkbox"/> |

☐ Amendment
Title Dielectric Composition For Forming Dielectric
Layer For Use In Circuitized Substrates

24 Pgs. Spec. 20 Claims 2 Shts. of Drawing
\$770.00 Filing Fee Attorney Lawrence R. Fraley
Docket EI-2-04-005
In Appln. Of R. Japp et al
Serial/Inter. Number _____
Filed Herewith

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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/812,889	03/31/2004	1756	770	EI-2-04-005	2	20	1

CONFIRMATION NO. 5016

Lawrence R. Fraley, IP Law Counsel
 Endicott Interconnect Technologies, Inc.
 0099/257-4 AA12
 1701 North Street
 Endicott, NY 13760

FILING RECEIPT



OC000000012994831

Date Mailed: 06/21/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Robert Japp, Vestal, NY;
 Kostas Papathomas, Endicott, NY;

Assignment For Published Patent Application

Endicott Interconnect Technologies, Inc., Endicott, NY;

Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted: 06/18/2004

Projected Publication Date: 10/06/2005

Non-Publication Request: No

Early Publication Request: No

Title

Dielectric composition for forming dielectric layer for use in circuitized substrates



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Date: 7/15/04
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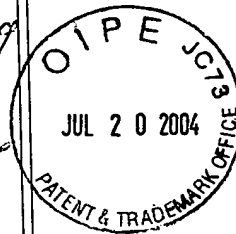
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| <input type="checkbox"/> Declaration _____ pgs. | <input type="checkbox"/> Draftsman w/Dwgs. |
| _____ signed _____ unsigned | <input checked="" type="checkbox"/> Cert. of Mailing |
| <input type="checkbox"/> Assignment w/Cover Pg. | <i>Change of</i> |
| <input type="checkbox"/> IDS/PTO-1449/Refs. | <i>Correspondence</i> |
| <input type="checkbox"/> Amendment | <i>Address</i> |

Title Dielectric Composition For Forming
Dielectric Layer For Use In
Circuit Substrates

_____ Pgs. Spec. _____ Claims _____ Shts. of Drawing
Filing Fee Attorney Lawrence Fraley
Docket RI-2-04-005
In Appln. Of R. Japp et al
Serial/Inter. Number 10,821,889
Filed 3/3/04

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Patent Office





Certificate of Mailing under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with United States Postal Service in an envelope addressed to:

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P.O. Box 1450
Alexandria, VA 22313-1450

On April 28, 2005.

Signature

Christine Lang

Typed or printed name of person of signing Certificate

EI-2-04-005 – Status Inquiry, Post Card, Copy of Application Return Post Card, Copy of Filing Receipt, Copy of Change of Correspondence Address Post Card, Stamped, Self-Addressed Envelope.

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